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Siliup Semiconductor

SP010N04BGNK

100V N-Channel Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	4.5mΩ@10V	100A
	6mΩ@4.5V	

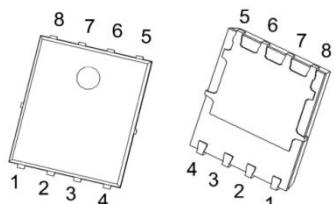
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

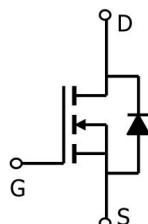
- Power switching application
- PWM Application
- DC-DC Converter

Package

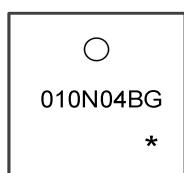


PDFNWB5X6-8L

Circuit diagram



Marking



010N04BG =Device Code
* =Month Code



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Absolute maximum ratings (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current(Tc=25°C)	I _D	100	A
Pulsed Drain Current ²	I _{DM}	400	A
Single Pulse Avalanche Energy ³	E _{AS}	100	mJ
Avalanche Current	I _{AS}	20	A
Total Power Dissipation ⁴ (Tc=25°C)	P _D	150	W
Thermal Resistance Junction-Case ¹	R _{θJC}	0.83	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID=250uA	100	---	---	V
Drain-Source Leakage Current	I _{DSS}	VDS=80V , VGS=0V , TJ=25°C	---	---	1	uA
Gate-Source Leakage Current	I _{GSS}	VGS=±20V , VDS=0V	---	---	±100	nA
Gate Threshold Voltage	V _{GS(th)}	VGS=VDS , ID=250uA	1.0	2.0	3.0	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	VGS=10V , ID=30A	---	4.5	5.7	mΩ
		VGS=4.5V , ID=20A	---	6	8	
Dynamic Characteristics						
Total Gate Charge (4.5V)	Q _g	VDS=50V , VGS=10V , ID=50A	---	97	---	nC
Gate-Source Charge	Q _{gs}		---	27	---	
Gate-Drain Charge	Q _{gd}		---	30	---	
Input Capacitance	C _{iss}	VDS=50V , VGS=0V , f=1MHz	---	4850	---	pF
Output Capacitance	C _{oss}		---	480	---	
Reverse Transfer Capacitance	C _{rss}		---	34	---	
Switching Characteristics						
Turn-On Delay Time	T _{d(on)}	VDD=50V , VGS=10V , RG=3Ω , ID=50A	---	24	---	ns
Rise Time	T _r		---	13	---	
Turn-Off Delay Time	T _{d(off)}		---	47	---	
Fall Time	T _f		---	11	---	
Source-Drain Diode Characteristics						
Diode Forward Voltage ²	V _{SD}	VGS=0V , IS=1A , TJ=25°C	---	---	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=50V,VGS=10V,L=0.5mH,IAS=20A
4. The power dissipation is limited by 150°C junction temperature



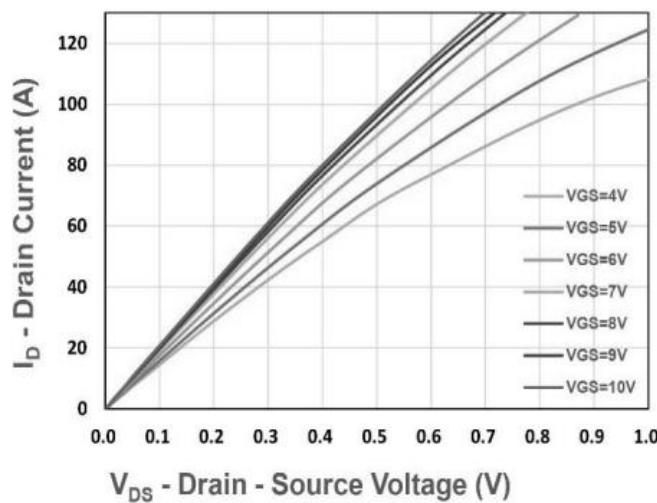
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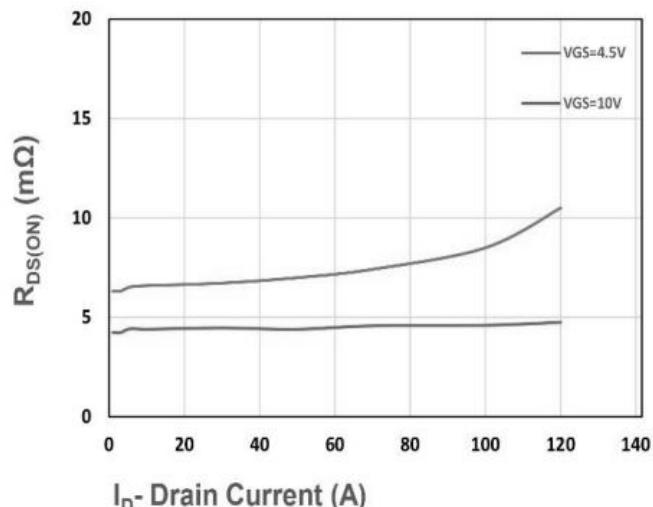
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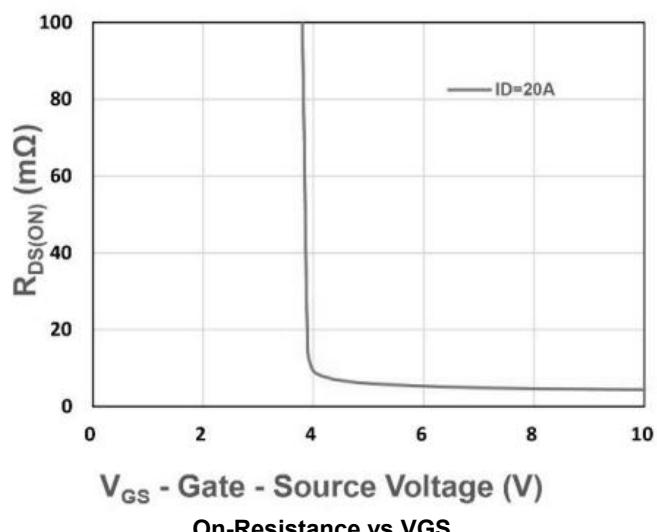
Typical Characteristics



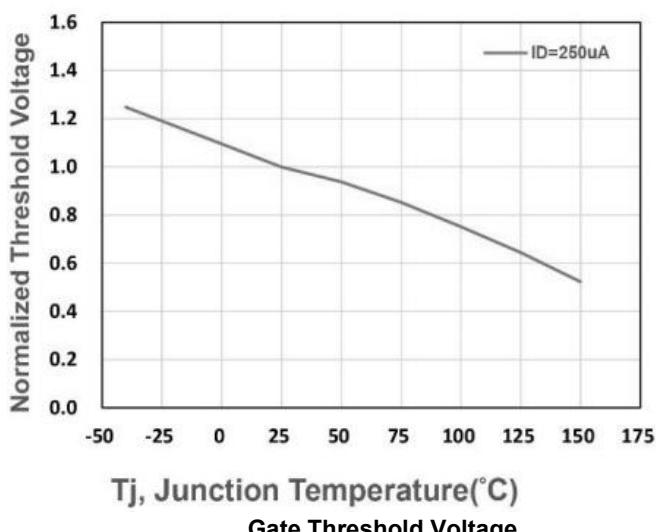
Typical Output Characteristics



On-Resistance vs.ID

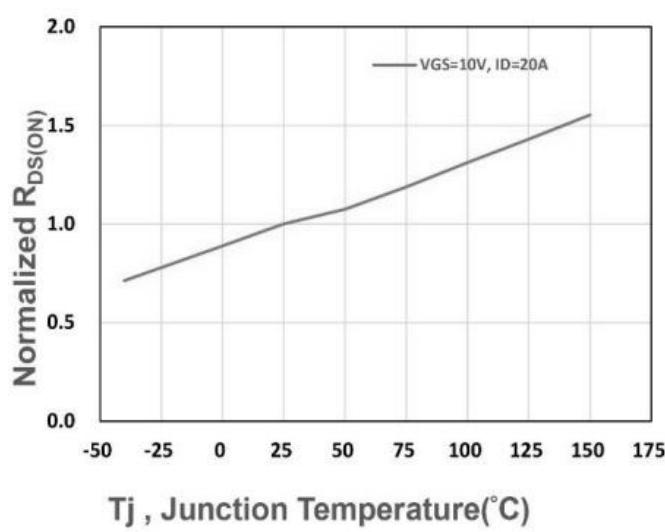


On-Resistance vs.VGS



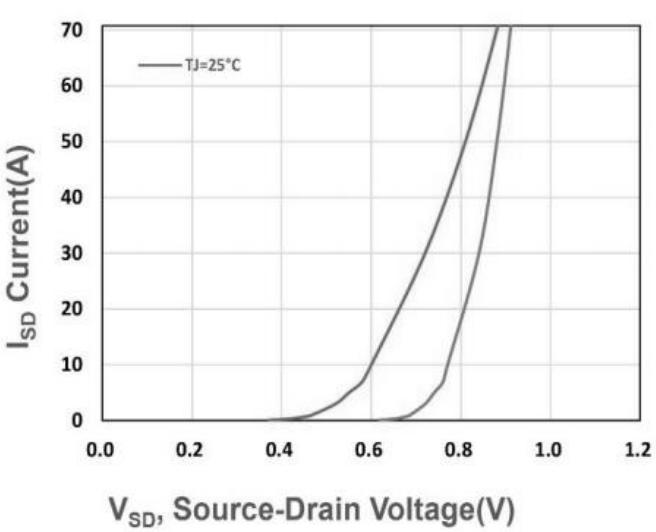
T_j, Junction Temperature(°C)

Gate Threshold Voltage



T_j , Junction Temperature(°C)

Drain-Source On-Resistance



V_{SD}, Source-Drain Voltage(V)

Source- Drain Diode Forward

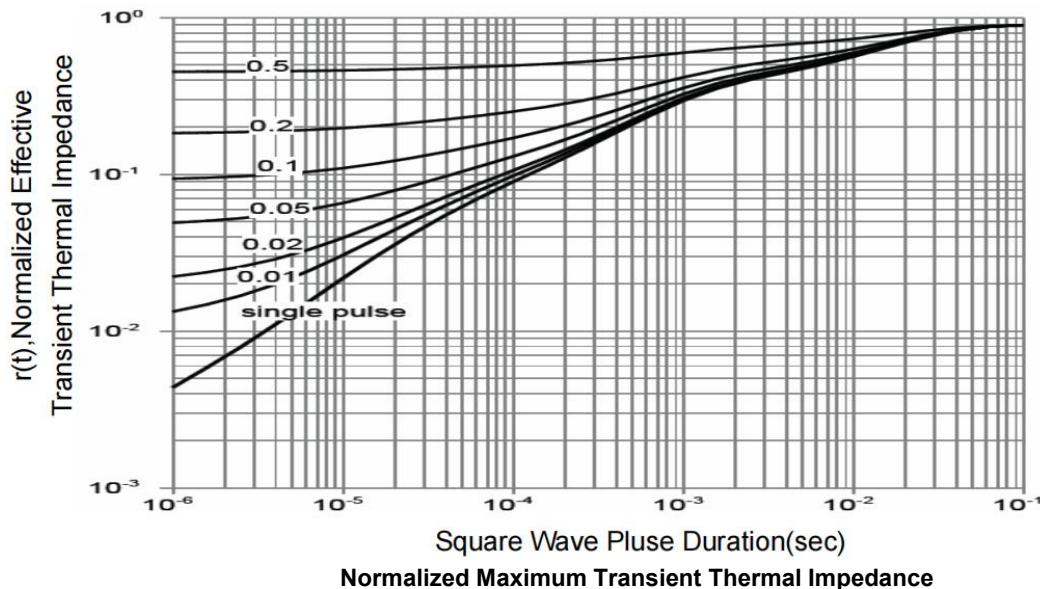
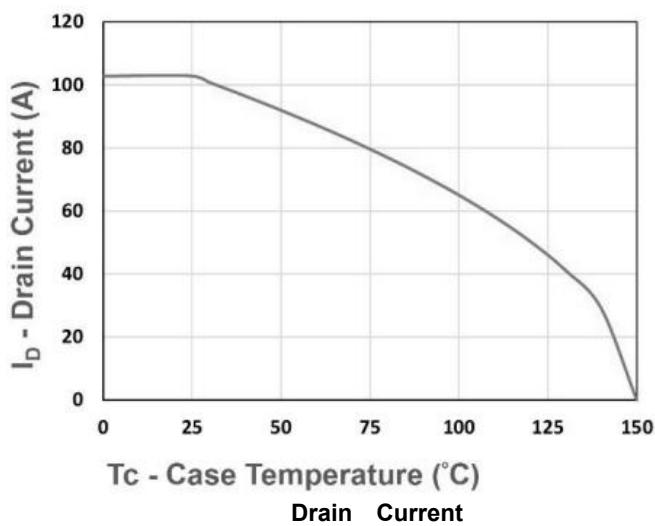
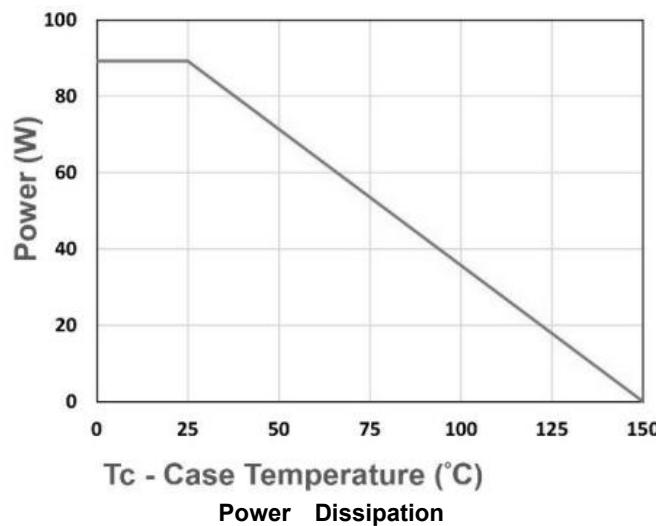
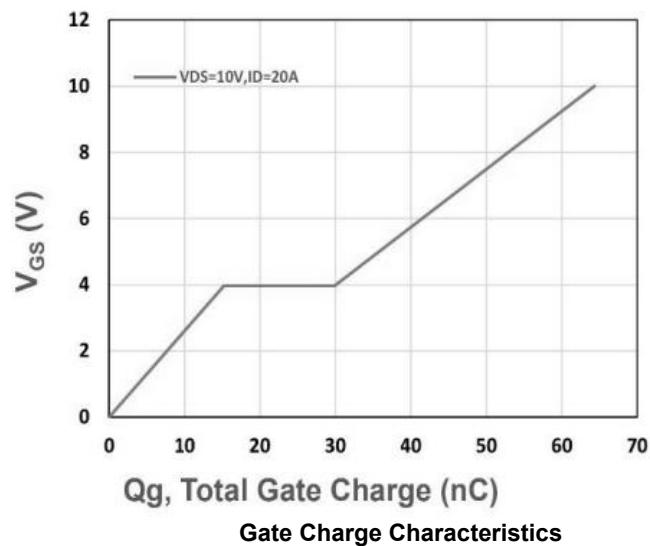
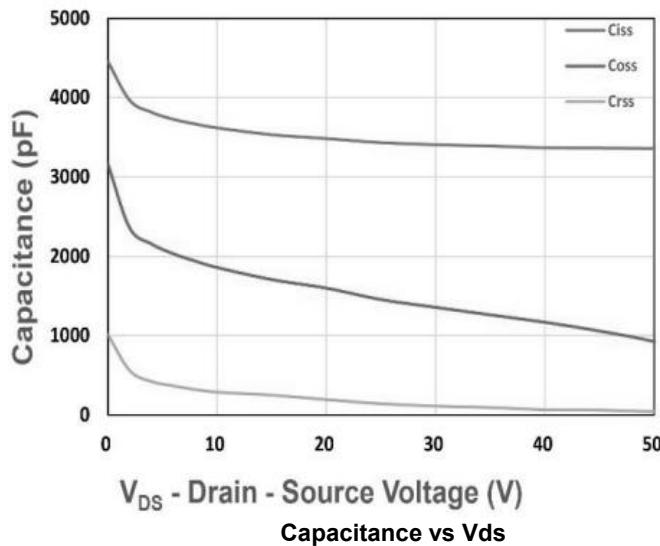


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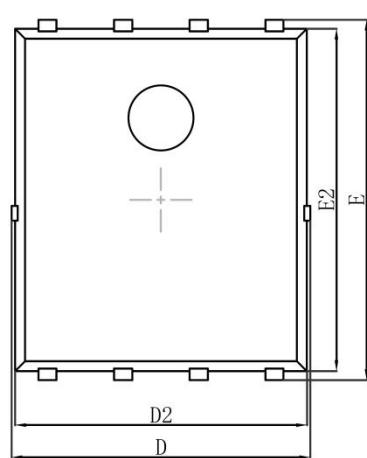
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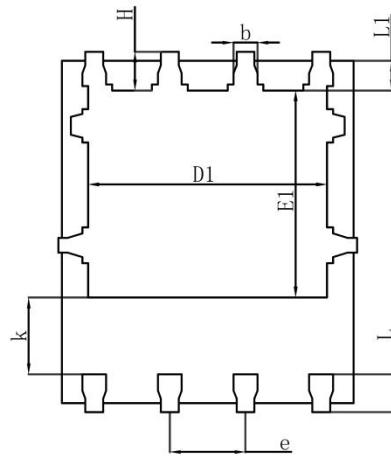
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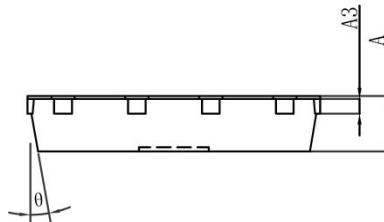
PDFNWNB5X6-8L Package Information



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°